

# SS34FL

DESCRIPTION

**PINNING** 

PIN

1

2

### **Surface Mount Schottky Barrier Rectifier**

Reverse Voltage - 40V Forward Current - 3.0A

#### **FEATURES**

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

#### **MECHANICAL DATA**

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight:27mg 0.00086oz

#### **Absolute Maximum Ratings and Electrical characteristics**

Ratings at  $25^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

1	2	-
Simplified outline	SMAF	and symbol

Cathode

Anode

Parameter	Symbols	SS34FL	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	40	٧
Maximum RMS voltage	V <sub>RMS</sub>	28	٧
Maximum DC Blocking Voltage	V <sub>DC</sub>	40	٧
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3.0	Α
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	80	А
Max Instantaneous Forward Voltage at 3 A	V <sub>F</sub>	0.45	٧
Maximum DC Reverse Current T <sub>a</sub> = 25°C at Rated DC Reverse Voltage T <sub>a</sub> =100°C	I <sub>R</sub>	0.3 5	mA
Typical Junction Capacitance 1)	Cj	450	pF
Typical Thermal Resistance 2)		40	°C/W
Operating Junction Temperature Range	Tj	-55 ~ +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 ~ +150	°C

- 1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
- 2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.





Fig.1 Forward Current Derating Curve

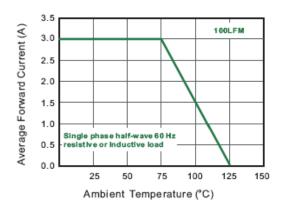


Fig.3 Typical Forward Characteristic

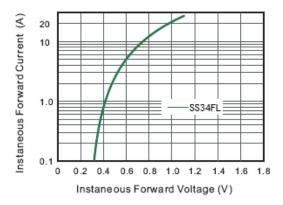


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

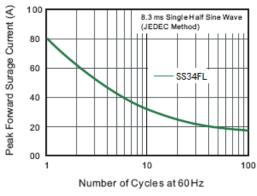


Fig.2 Typical Reverse Characteristics

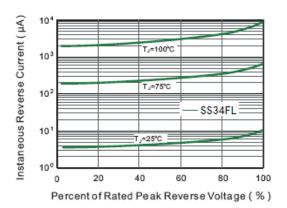


Fig.4 Typical Junction Capacitance

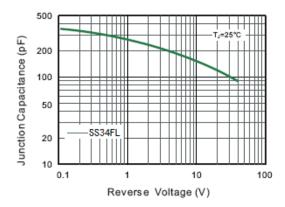
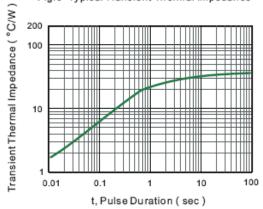


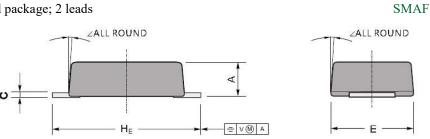
Fig.6- Typical Transient Thermal Impedance

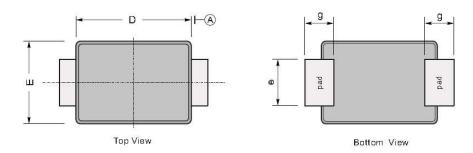




## PACKAGE OUTLINE

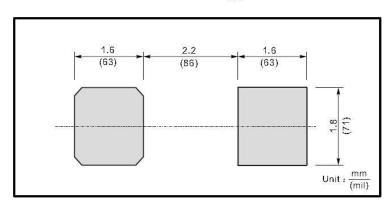
Plastic surface mounted package; 2 leads





UNIT		Α	С	D	Е	е	g	H∈	<b>Z</b>
mm -	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	8.0	4.4	
mil	max	43	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

## The recommended mounting pad size



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## 单击下面可查看定价,库存,交付和生命周期等信息

>>SHIKUES(时科)